



Part No. 1110087

144 Pin VQFP to PGA Adapter

FEATURES:

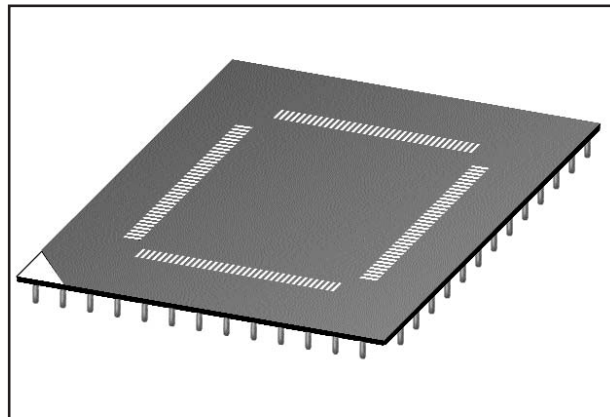
- Convert surface mount VQFP packages to a 13 x 13 PGA footprint.
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for panelized form or for mounting of consigned chips.

SPECIFICATIONS:

- Adapter body is FR-4 with 1 ounce minimum Copper traces.
- Pads are ENIG (Gold over Nickel) Plated to eliminate coplanarity concerns.
- Pins are Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-00.
- Pin plating is 200µ [5.08µm] min. Tin Per ASTM B 545 Type 1 or Tin/Lead 93/7 per ASTM B 545 over 100µ [2.54µm] Nickel per SAE-AMS-QQ-N-290.
- Operating temperature=221°F [105°C].

MOUNTING CONSIDERATIONS:

- Suggested PCB hole size=.028 ± .003 [.71 ± .08] dia.
- Will plug into standard PGA sockets.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

Specify Part No. 1110087

-OR-

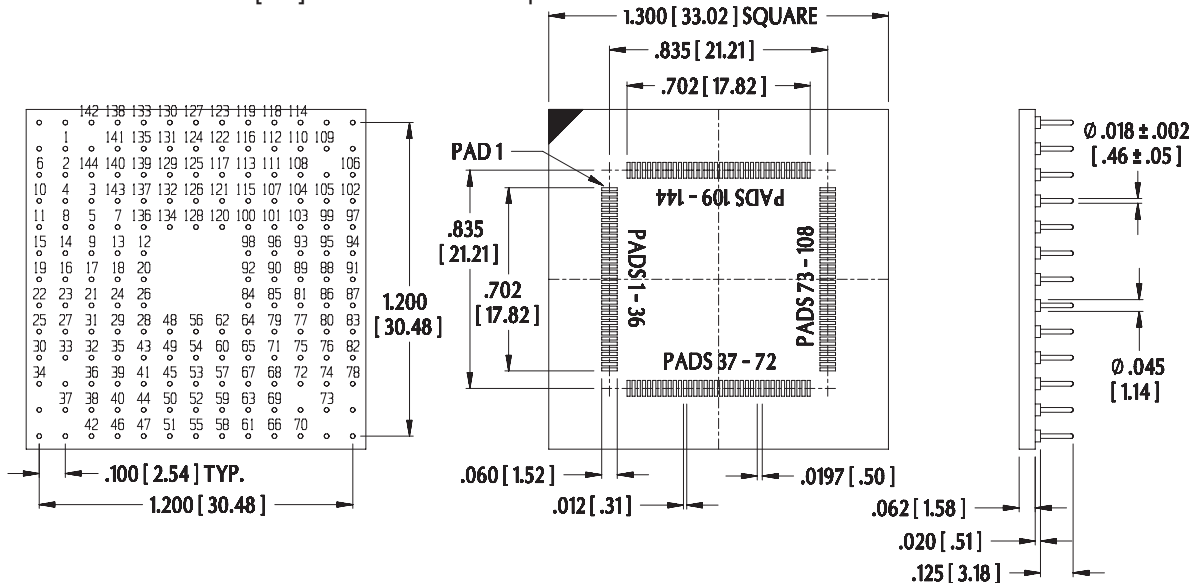
1110087-P for panelized form when ordering

ALL DIMENSIONS: INCHES [MILLIMETERS]

Tolerances:

- Row-to-row: ± .003 [± .08]
- Pin-to-pin: ± .003 [± .08] non-cumulative
- All others: ± .005 [.13] unless otherwise specified

Specify Part Number 144-PGM13095-30 for wire wrap PGA socket



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT

TOP (QFP) SIDE



Bristol, PA USA
TEL: (215) 781-9956
FAX: (215) 781-9845



18040
REV. H